

Instruction for Use NQPACK, YQPACK, HQPACK, and YQSOCKET

1. Temperature of IC package will rise during emulation test. This may cause null function in IC package. Cool NQPACK, IC package, and HQPACK assembly with an electric fan to recover its function.
NQPACK, YQPACK, HQPACK, and YQSOCKET were developed for development and emulation test. Therefore, these connectors and socket should not be used in the final products that will be parked in the market place, and are not satisfactory for domestic electrical safety rules or EMI requirements.
2. Make it sure whether your IC package can be installed on NQPACK that you are going to use. Regarding the applicable package dimensions, refer to the product catalog.
3. Hold NQPACK, YQPACK, or HQPACK by hand when you take it out of an individual box. Then remove packing materials.
4. Packing boxes will be damaged when the boxes are kept under the room temperature more than 50 degree Celsius for long time. So, stock them under the room temperature lower than 40 degree Celsius and no sunlight will reach to the stocking place.
5. Check if any burrs appear on each corner of IC package. If any burrs are found, remove them with a knife before installing the package on NQPACK.
6. Check if any IC package leads are damaged every time when you install it on NQPACK since the leads are fragile and easily damaged after a few times of installation and extraction of the package.
7. Screw NQPACK, YQPACK, or HQPACK loosely first with the driver attached or a torque driver, then tightly fasten them. Tightening torque should be $0.054\text{N}\cdot\text{m}$ ($0.55\text{kgf}\cdot\text{cm}$) and should be as equal as possible on each screw. If tightened strongly one screw only, open contact problem may cause between IC leads and the socket contacts.
8. Lead pins of YQPACK can be damaged from twisting or shaking force when extracting YQSOCKET from YQPACK. Therefore, YQSOCKET should be extracted from YQPACK little by little at four corners with a (-) driver.
9. Four mounting holes of 2.3 or 3.3 mm diameter must be drilled to fix YQPACK onto PCB. The place underneath the screw head of 3.8 mm diameter is wiring restriction area.
10. Cover NQPACK with HQPACK when soldering NQPACK to prevent it from vaporizing flux.
Recommending soldering temperature profile:
 - Reflow 260 degree Celsius for 10 seconds max.
 - Manual 350 degree Celsius for 5 seconds max. / LeadHeat air soldering is also recommendable.
11. Do not clean NQPACK, YQPACK, HQPACK, or YQSOCKET since cleaning solvent will remain in the connectors.
12. IC package could not be placed in between NQPACK and YQPACK.
13. NQPACK, IC package, and HQPACK assembly is for emulation test application.
14. NQPACK, YQPACK, HQPACK, and YQSOCKET could not be used under vibration or shocking environment.

